

1 Electronic Supplementary Information (ESI)

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3 **On the role of local heating on cathode degradation during the** 4 **oxygen reduction reaction in solid acid fuel cells**

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15 **S1: Mass normalized current density**

16 CP/Pt@CDP_{porous}-MEAs achieve current densities during cell I-V characterization of up 150 mA cm⁻²
17 with a platinum loading of 64 µg cm⁻² per electrode (as published previously).^[1] This results in a
18 platinum normalized current density of about 2300 mA mg_{Pt}⁻¹. State of the art solid acid fuel cells with
19 a powder electrode were reported by Papandrew et al. with maximum current densities of 1.2 A cm⁻²
20 during I-V characterization and a platinum loading of 1.75 mg cm⁻², resulting in 685 mA mg_{Pt}⁻¹.^[2]

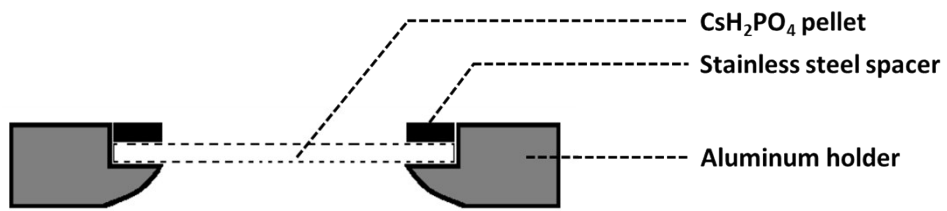
21 **S2: Electrode generation using a spray drying process**

22 Set of spray dryer and precursor parameters used to deposit porous CsH₂PO₄ electrodes as reported previously. ^[1]

Precursor parameters			Spray dryer parameters			
CsH ₂ PO ₄ conc.	Methanol content	PVP conc.	Temp.	Carrier gas flow rate	Precursor solution flow rate	Atomizer mesh size
10 g l ⁻¹	44 wt%	0.3 g l ⁻¹	303 K	80 l min ⁻¹	1.5 ml min ⁻¹	4 µm

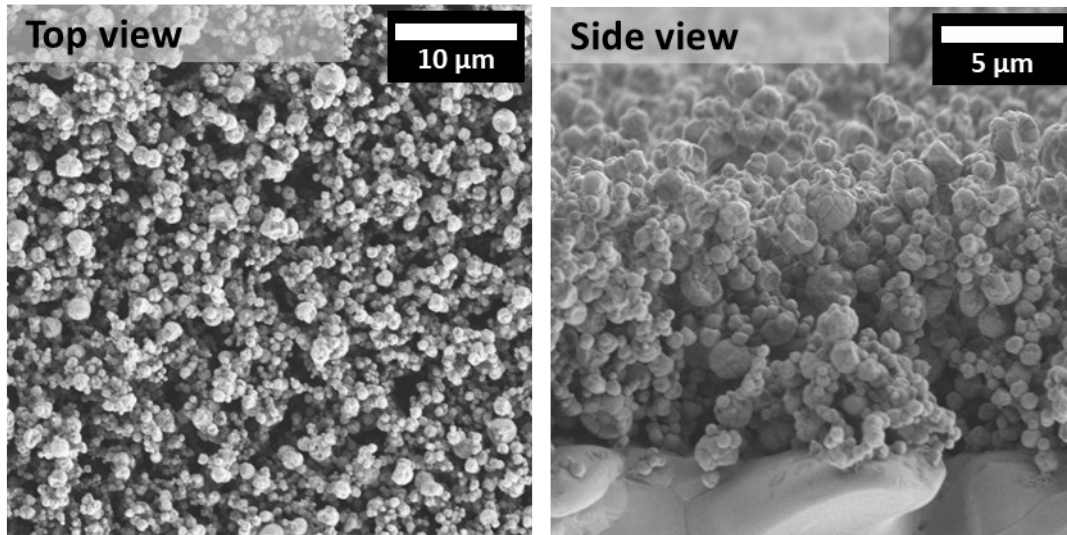
23

24 Previously optimized precursor and spray parameters were used for the spray drying process.^[1] To
25 generate a 15 µm thick porous layer, a spraying time of 100 min was needed. The porous structure
26 was applied to both sides of a CsH₂PO₄ pellet one by one. A costume made holder was used to prevent
27 damage to the already modified side.



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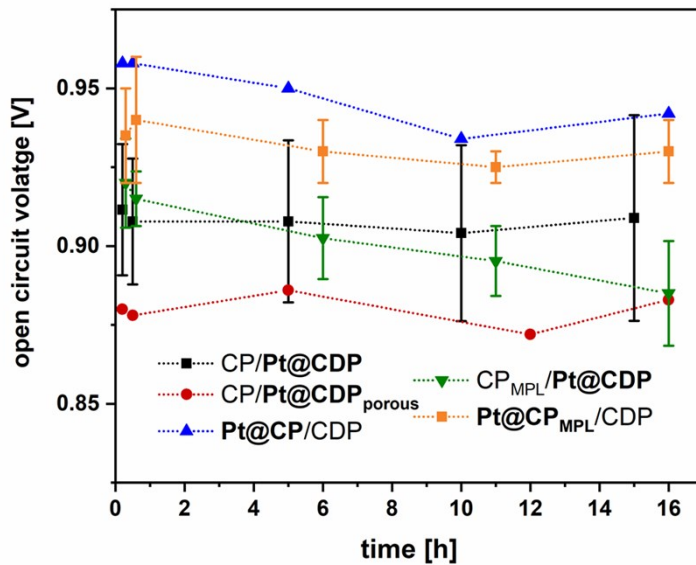
2 Custom made cell holder to protect the generated porous structure.



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4 Representative SEM micrographs of the porous electrode after the spray drying process.

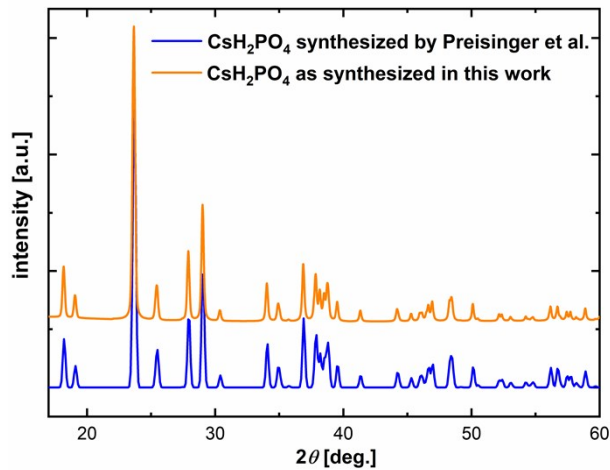
5 S3: Open circuit voltage



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7 Open circuit potential for all MEA types over time. No significant change in the open circuit voltage was detected within the
8 measurement time.

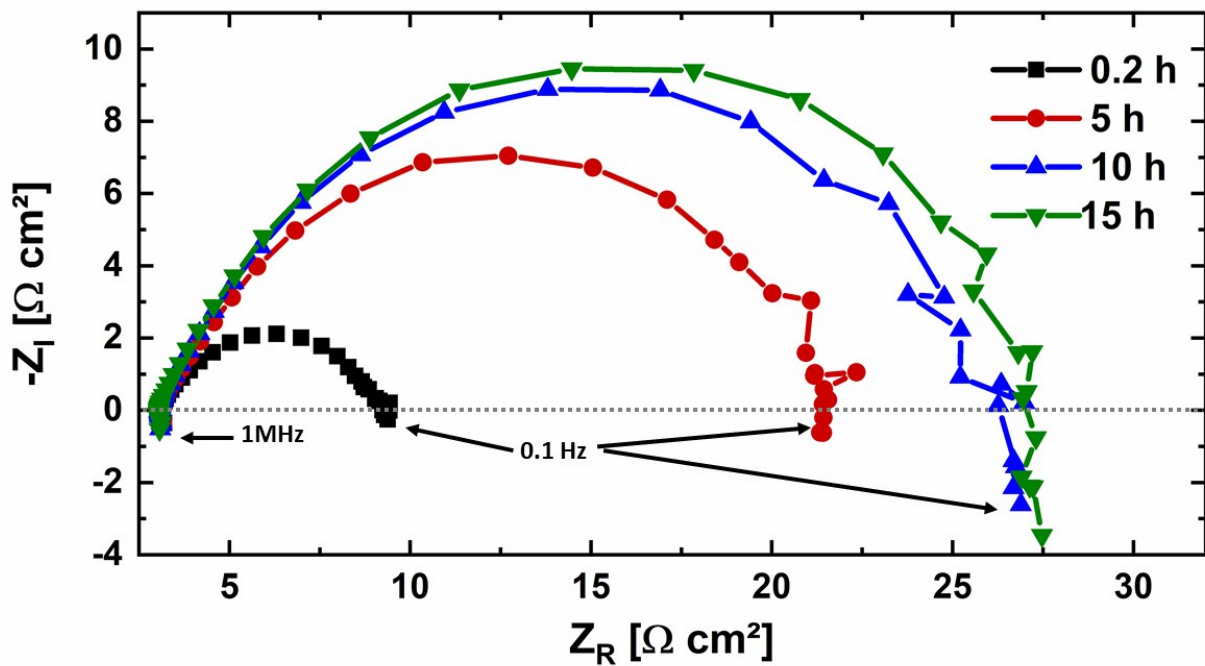
1 S4: X-ray diffraction experiment



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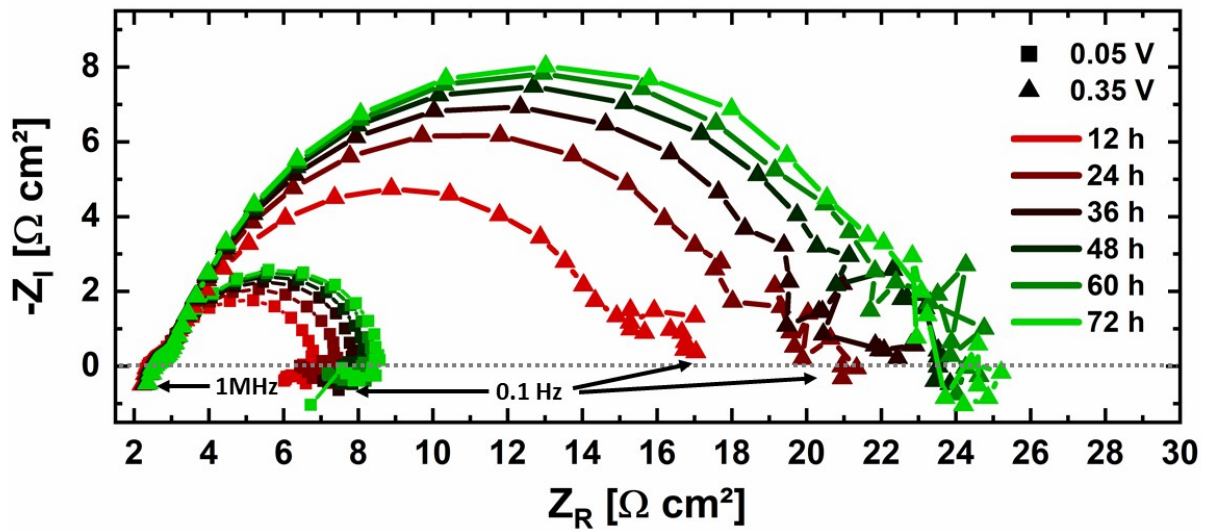
3 X-ray diffraction experiments to control the purity of the CsH₂PO₄ after synthesis at 25°C. A G670 Guinier Camera (Huber)
4 using copper K_α radiation ($\lambda = 1.541 \text{ \AA}$) and a 2θ -range between 15° and 70° was used. Diffractogram was compared to results
5 of pure CsH₂PO₄ at 25°C published by Preisinger et al.^[5]

6 S5: Impedance measurements

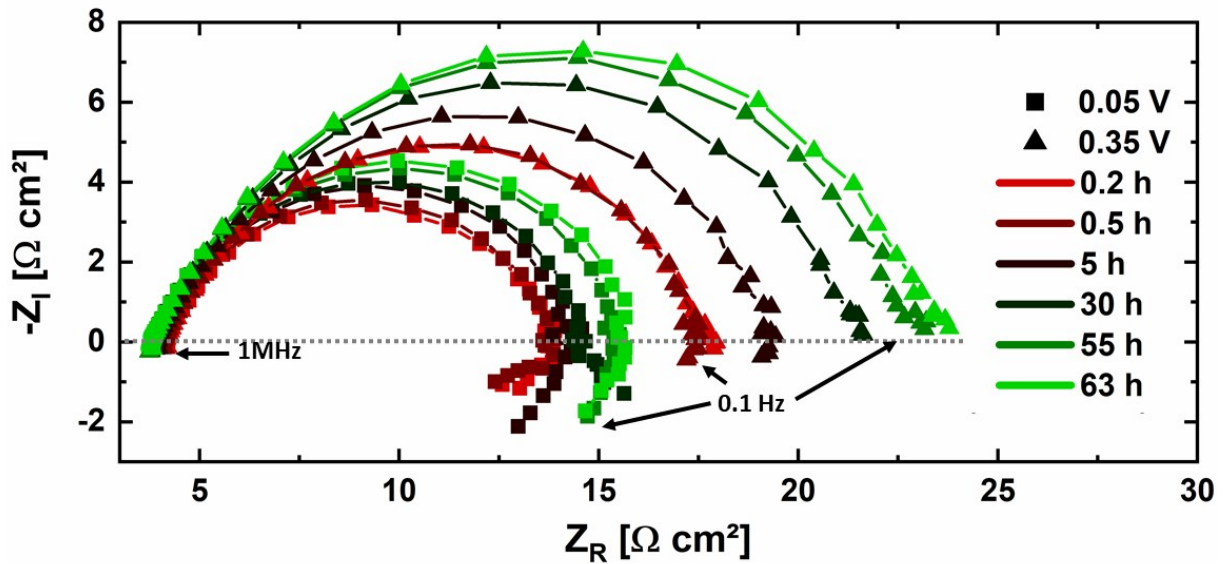


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8 CP/Pt@CDP: staircase potential electrochemical impedance spectroscopy (SPEIS) after different times for voltages of 0.35 V.
9 Voltage of 0.05 V is discussed in detail in the manuscript.

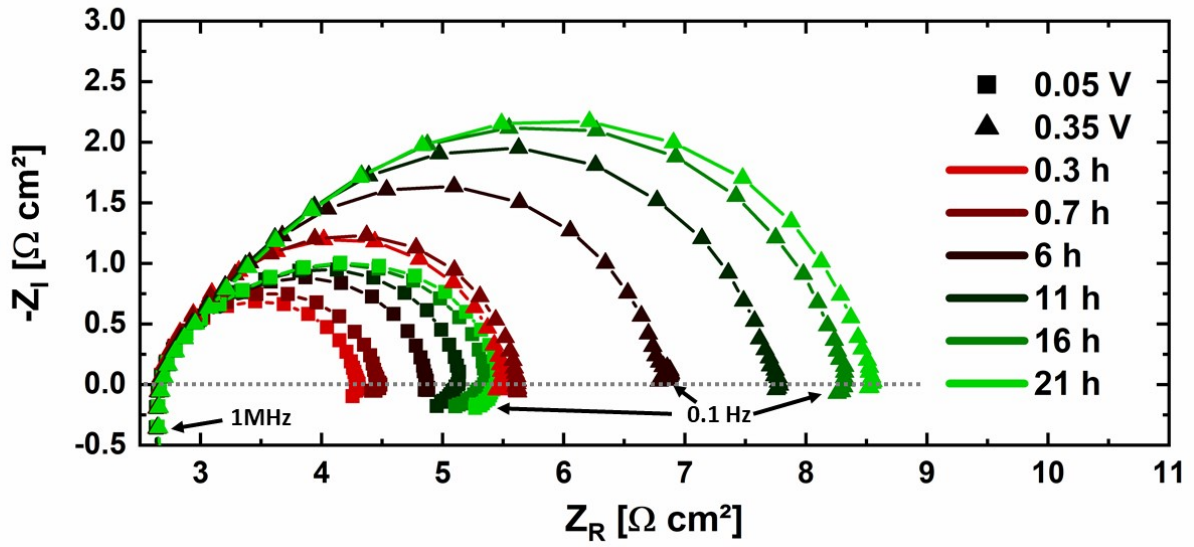


2 CP/Pt@CDP_{porous}: staircase potential electrochemical impedance spectroscopy (SPEIS) after different times for voltages $U =$
 3 0.05 V and 0.35 V. Time is indicated by the colour and the respective voltage by the symbol.



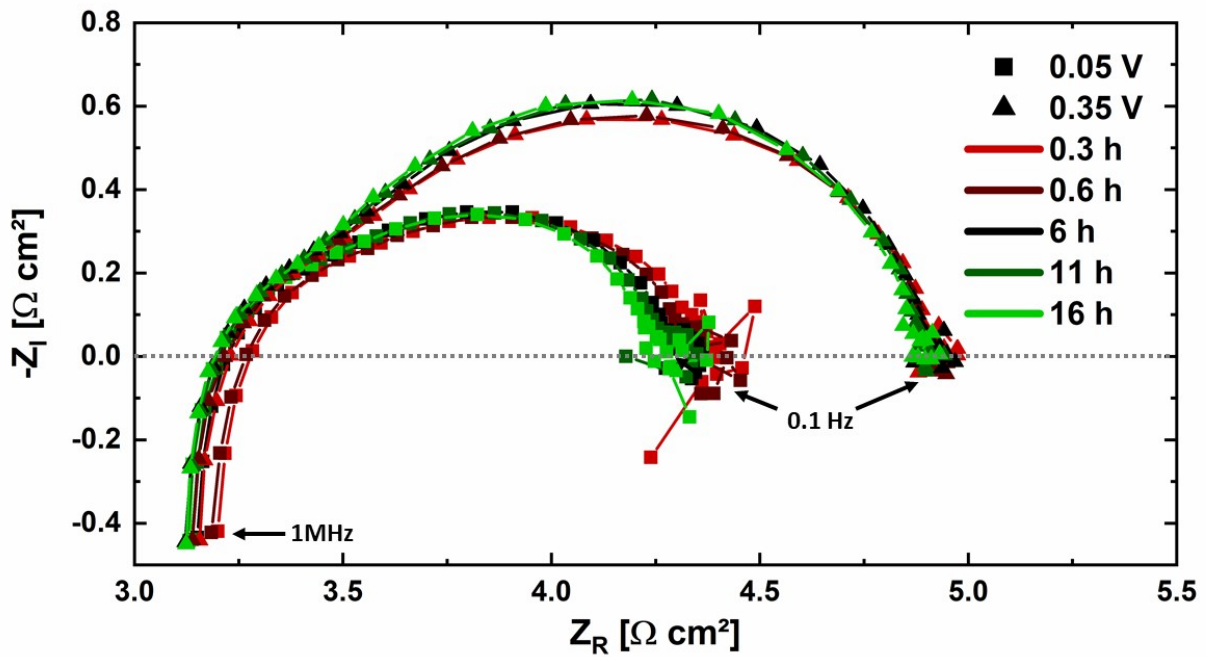
5 Pt@CP/CDP: staircase potential electrochemical impedance spectroscopy (SPEIS) after different times for voltages $U =$ 0.05 V
 6 and 0.35 V. Time is indicated by the colour and the respective voltage by the symbol.

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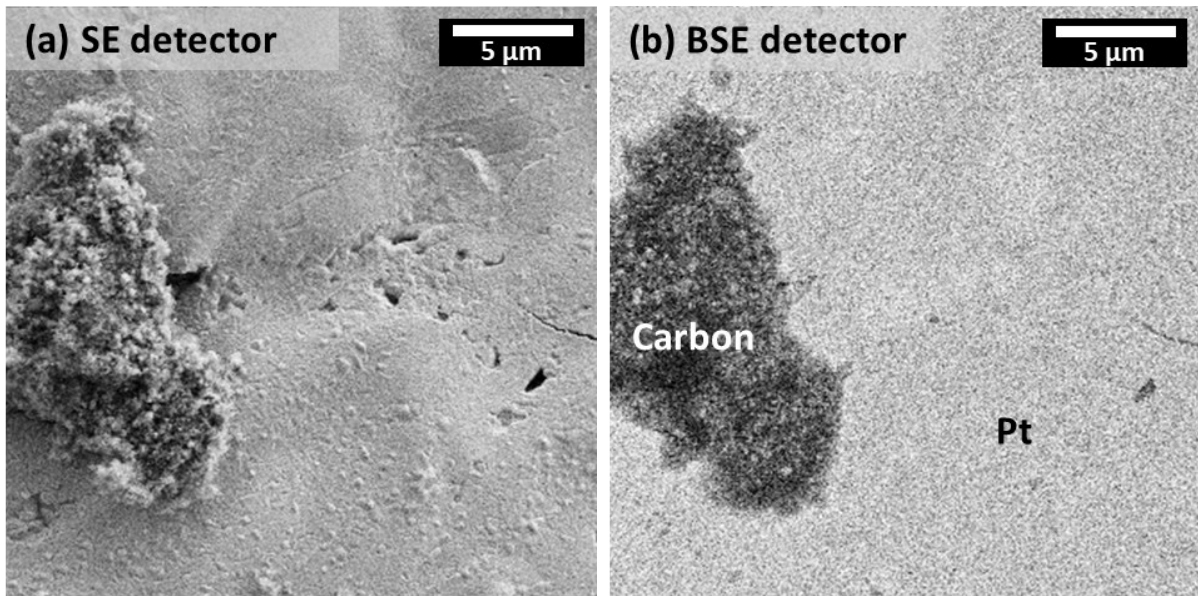
3 Pt@CP_{MPL}/CDP-MEA: staircase potential electrochemical impedance spectroscopy (SPEIS) after different times for voltages U =
4 = 0.05 V and 0.35 V. Time is indicated by the colour and the respective voltage by the symbol.



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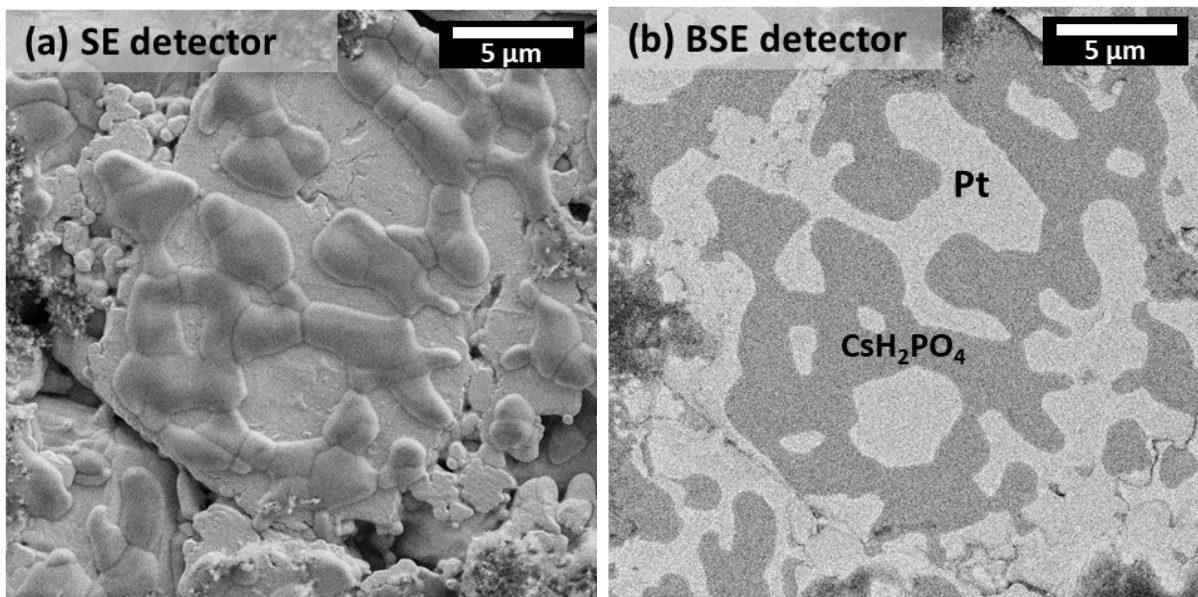
6 CP_{MPL}/Pt@CDP: staircase potential electrochemical impedance spectroscopy (SPEIS) after different times for voltages U =
7 0.05 V and 0.35 V. Time is indicated by the colour and the respective voltage by the symbol.

1 **S6: SEM analyzation of CP_{MPL}/Pt @CDP**



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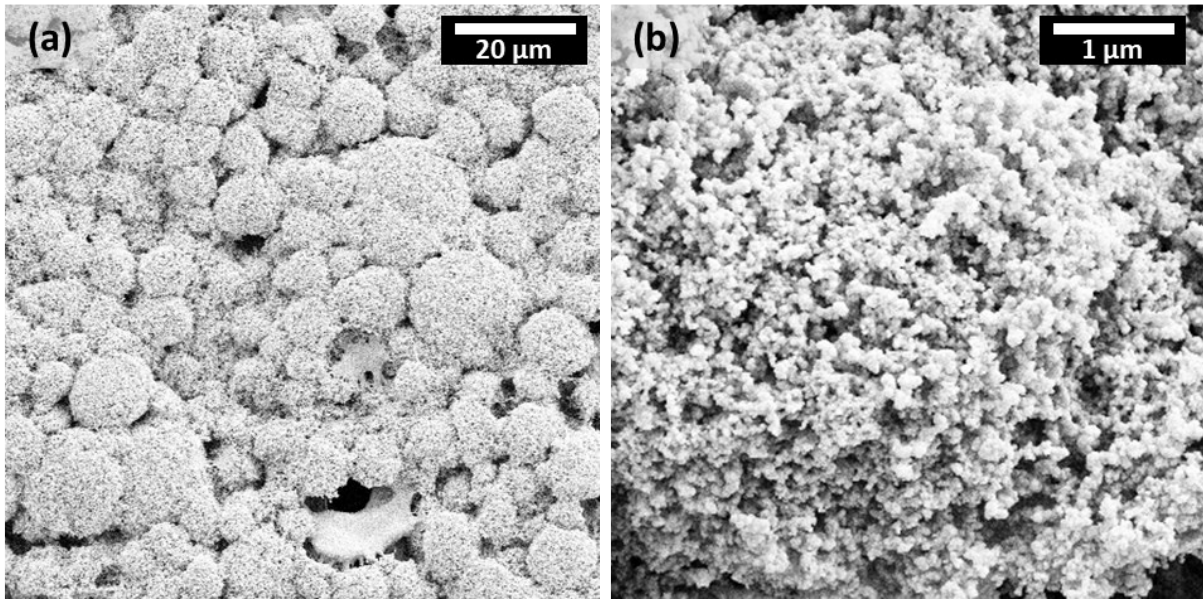
3 SEM micrographs of the CP_{MPL}/Pt@CDP anode after carbon paper removal. (a) Secondary electron (SE) detector. (b) Back
4 scattering electron (BSE) detector. Relevant phases are marked in (b).



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6 SEM micrographs of the CP_{MPL}/Pt@CDP cathode after carbon paper removal. (a) Secondary electron (SE) detector. (b) Back
7 scattering electron (BSE) detector. Relevant phases are marked in (b).

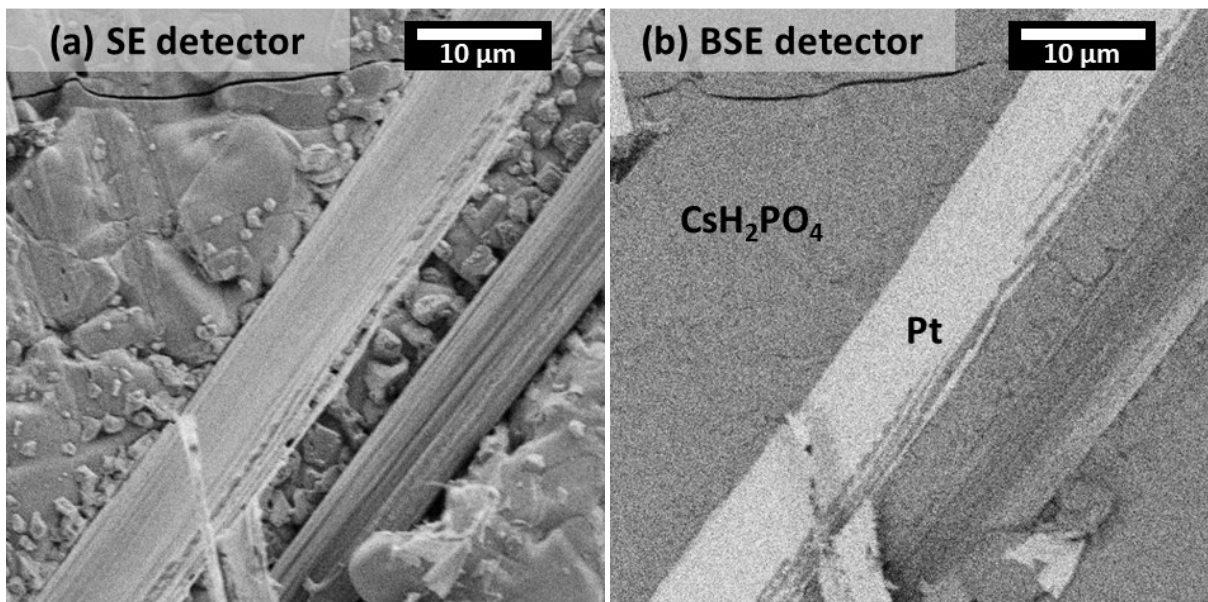
1 **S7: SEM analyzation Pt@CP_{MPL}/CDP**



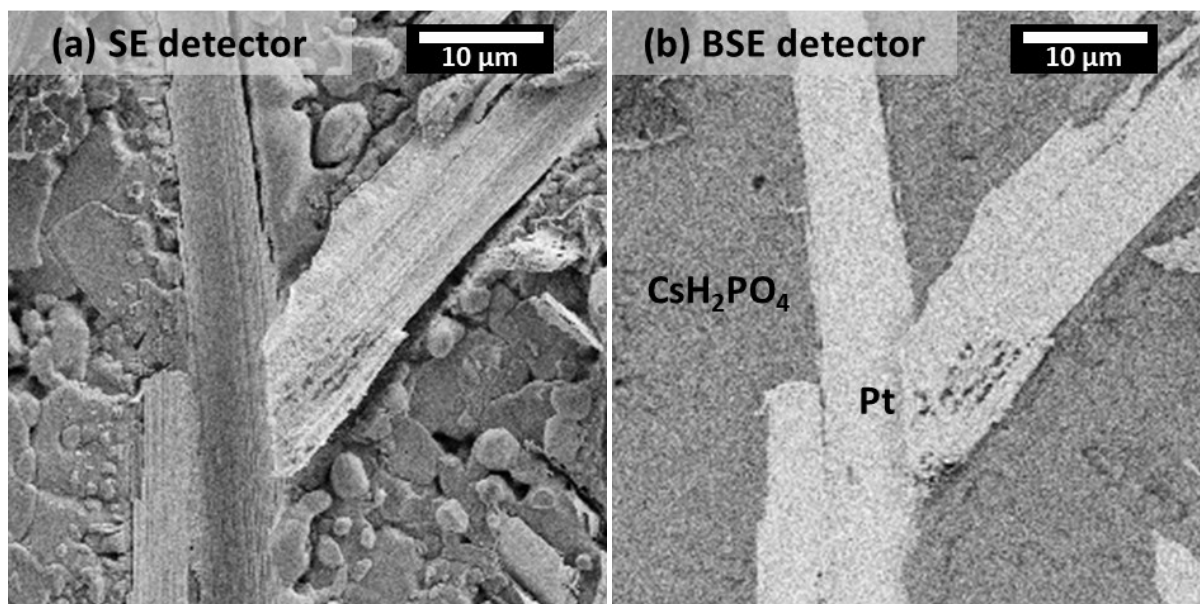
2
3 SEM micrographs of the CP_{MPL} after platinum deposition.

4 **S8: SEM analyzation Pt@CP/CDP**

5 Two different sections of the Pt@CP/CDP cathode surface were analyzed by SEM. During removal
6 of the carbon paper, platinum occasionally detachment from the carbon fiber leaving behind a
7 platinum coated imprint. Morphological changes of the electrolyte close to the imprint are visible.



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9 SEM micrographs of the Pt@CP/CDP cathode after carbon paper removal. (a) Secondary electron (SE) detector. (b) Back
10 scattering electron (BSE) detector. Relevant phases are marked in (b).

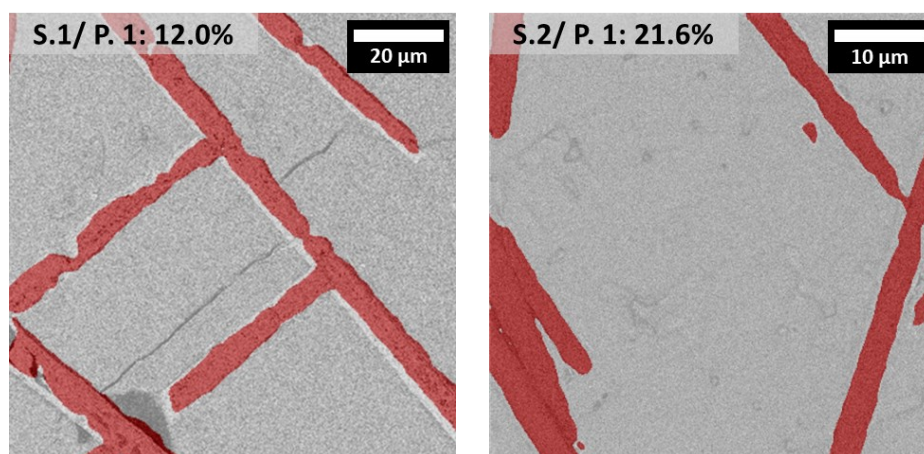


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2 SEM micrographs of the **Pt@CP/CDP** cathode after carbon paper removal. (a) Secondary electron (SE) detector. (b) Back
 3 scattering electron (BSE) detector. Relevant phases are marked in (b).

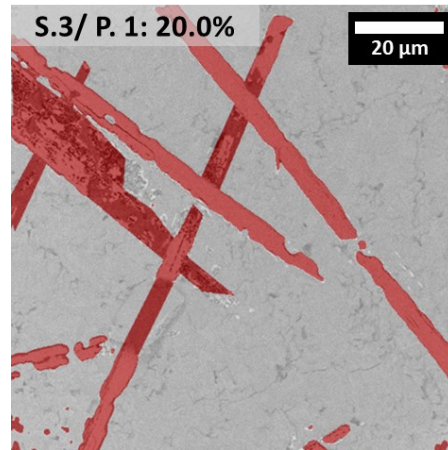
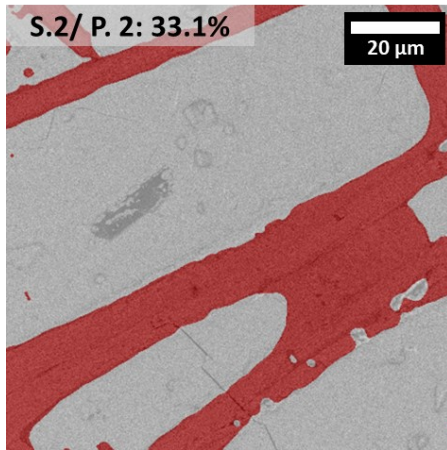
4 **S9: Contact area CsH_2PO_4 – Platinum**

5 After measuring platinum plated carbon paper (CP) electrodes, the carbon paper was removed prior
 6 to scanning electron microscope (SEM) investigation. At areas where carbon strands were in contact
 7 with the CsH_2PO_4 surface, imprints can be seen on the surface. During the removal process, platinum
 8 detached from the carbon fibers and is present at the electrolyte surface. Using a back-scattering
 9 detector, a high material contrast could be achieved for magnifications between 500 and 1000
 10 depending on the sample, making an image processing with the image J software (Version 1.52t)
 11 possible. Representative overlays of the SEM micrographs and contact area determined by the image
 12 processing are shown. There is a large variation between the samples, resulting in a relatively large
 13 standard deviation. Since this analysis was designed to provide a rough overview of the area coverage
 14 the scale of 7 measurements was considered sufficient by the authors.



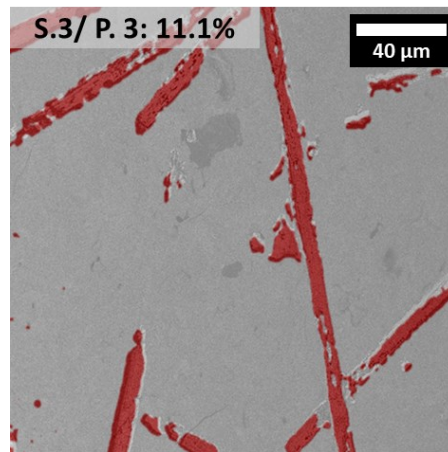
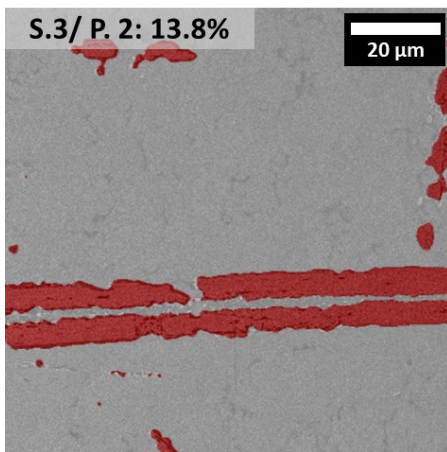
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16 Representative overlays of the SEM micrographs and contact area determined by the image processing for sample 1, position
 17 1 (S.1/P.1) and sample 2, position 1 (S.2/P.1).



1

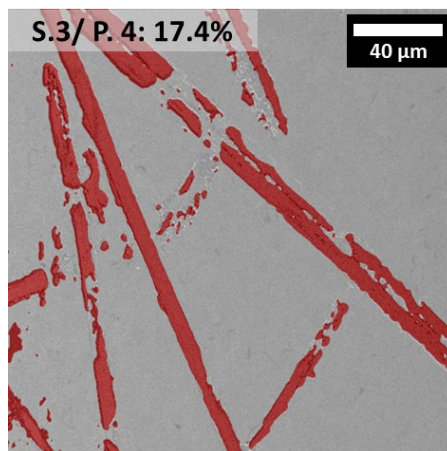
2 Representative overlays of the SEM micrographs and contact area determined by the image processing for sample 2, position
3 2 (S.2/P.2) and sample 3, position 1 (S.3/P.1).



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5 Figure S 3 Representative overlays of the SEM micrographs and contact area determined by the image processing for
6 sample 3, position 2 (S.3/P.2) and sample 3, position 3 (S.3/P.3).

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9 Figure S 4 Representative overlays of the SEM micrographs and contact area determined by the image processing for
10 sample 3, position 4 (S.3/P.4).

- 1 Results of analyzing a total of 7 different locations on 3 different cells are summarized in the table.
 2 Overall, an area coverage of $18 \pm 9\%$ was obtained. Which represents a considerable decrease of the
 3 platinum coverage compared to the completely covered platinum thin film electrodes.
 4 Results of analyzing a total of 7 different locations on 3 different cells. An overall coverage of $18 \pm 9\%$ was obtained.

Sample	Position	Area coverage [%]
1	1	12.0
2	1	21.6
2	2	33.1
3	1	20.0
3	2	13.8
3	3	11.1
3	4	17.4

5

6 S10: Calculation of the sheet resistance

7 At 20°C , platinum bulk metal has an electrical resistivity of $1.05 \cdot 10^{-7} \Omega \text{ m}$. With a thickness of 30 nm,
 8 the electrical resistivity of the platinum thin film can be described in good approximation with bulk
 9 behavior.^[3] With a temperature coefficient " α " of $0,003927 \text{ K}^{-1}$ and $\Delta T = 220^\circ\text{C}$, the resulting electrical
 10 resistivity " ρ " at operating temperature of 240°C can be calculated by: ^[4]

$$11 \rho_{240^\circ\text{C}} = \rho_{20^\circ\text{C}} * (1 + \alpha \Delta T) = 1,05 * 10^{-7} * (1 + 0,86394) \Omega \text{ m} = 1,98 * 10^{-7} \Omega \text{ m}$$

12 The resulting sheet resistance for a layer thickness of $t = 30 \text{ nm}$ can be calculated by:

$$13 R_{S,240^\circ\text{C}} = \frac{\rho_{240^\circ\text{C}}}{t} = \frac{1,98 * 10^{-7} \Omega \text{ m}}{3,0 * 10^{-8} \text{ m}} = 6,6 \Omega$$

14

15 References

- 16 [1] Wagner, M.; Dreßler, C.; Lohmann-Richters, F. P.; Hanus, K.; Sebastiani, D.; Varga, A.; Abel, B., *J.*
 17 *Mater. Chem. A*, (2019) **7**, 27367.
 18 [2] Papandrew, A. B.; Chisholm, C. R.I.; Elgammal, R. A.; Özer, M. M.; Zecevic, S. K., *Chem. Mater.*, (2011)
 19 **23**, 1659.
 20 [3] Avrekh, M.; Monteiro, O.R.; Brown, I.G., *Applied Surface Science*, (2000) **158**, 217.
 21 [4] Serway, R. A., *Principles of physics*, (1998-), Fort Worth, Saunders College Pub.
 22 [5] Preisinger, A.; Mereiter, K.; Bronowska, W., *MSF*, (1994) **166-169**, 511.

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